

ABSTRACT OF THE DISCLOSURE

MANUFACTURING APPARATUS AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

A wire bonding apparatus (10) includes: a capillary (18), performing predetermined processing on a workpiece (100) and movable with respect to the workpiece (100); an optical mechanism (24), moving together with the capillary (18); and a controller (28). The optical mechanism (24) includes: a first imaging unit, acquiring a first image obtained by imaging a standard point (Ps) set within an imaging range; and a second imaging unit, acquiring a second image obtained by imaging a reference point (Pr) formed at a predetermined distance from the capillary (18). The controller (28) positions the capillary (18) with respect to the workpiece (100) based on the first image, and calculates a positioning correction amount of the capillary (18) based on the second image.

Representative drawing: FIG. 3